

Advanced Packaging Update: Market and Technology Trends

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The second volume of the Advanced Packaging Update presents the financials for OSATs. The latest trends in high-performance computing are discussed with a focus on developments in artificial intelligence packaging and assembly. A section examines network system packaging options, including fan-out on substrate and Si interposers. An update on activities in through silicon vias (TSVs) and developments in direct bonding for image sensors are discussed. A special section examines the growing market for micro LEDs. TechSearch International's annual survey on substrate design rules is highlighted, with special coverage of suppliers of organic flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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ACCESS, ASE Materials, AT&S, Daeduck, Daisho Denshi, Fujitsu Interconnect Technologies, Haesung DS, Ibiden, i3 Electronics, Kinsus, KCC, Kyocera, LG Innotek, Nan Ya PCB, SEMCO, SCC, Shinko Electric, Simmtech, Toppa Printing, Unimicron

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